

FLUX, METHOD FOR APPLYING FLUX, AND METHOD FOR MOUNTING
SOLDER BALL

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ABSTRACT

Provided is flux that can be discharged using an inkjet method and that is capable of bonding to an adherend after application. This flux includes 5-50 mass% of a solid solvent having a melting point of 60°C or less, 50-80 mass% of a solvent, 5-10 mass% of an organic acid, 10-30 mass% of an amine, and 0-5 mass% of a halide, the flux forming a liquid having a high viscosity of 5 Pa·s or higher at 25°C, and forming a liquid having a low viscosity of 50 mPa·s or less at 100°C.

[No drawing is available]